

Abstract

A resin molding apparatus (1) includes: a resin supply mechanism (26) configured to supply powder resin to a resin containing section (24) including a release film (F) and a frame (24a) placed on the release film (F); a resin molding mechanism (3) including a molding die (M) that includes an upper die (UM) and a lower die (LM) facing the upper die (UM) and configured to place between the upper die (UM) and the lower die (LM) the release film (F) with the powder resin on the release film (F) for resin molding; and a resin collecting mechanism (6) configured to suck the powder resin from the release film (F) for collection before the resin molding mechanism (3) places the release film (F) on the molding die (M).

[Fig. 1]